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ABSTRACT

WAFER TRANSFER APPARATUS

A wafer transfer apparatus comprising a first ultraviolet irradiation unit capable of irradiating and exposing ultraviolet light to a protective tape; a positioning unit capable of effecting positioning of a wafer; a mount unit capable of uniting the wafer with a ring frame; a protective tape peeling unit capable of peeling a protective tape from the wafer surface; and a second ultraviolet irradiation unit capable of irradiating and exposing ultraviolet light to a dicing tape. The provided wafer transfer apparatus is one of enhanced general applicability which can be applied to not only the conventional postdicing processing but also a predicing processing, and which, irrespective of the types of employed protective tape and dicing tape, can continuously and automatically transfer the wafer having the protective tape stuck thereto to the dicing tape and the ring frame and further peel the protective tape from the wafer surface.

(FIG.1)

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